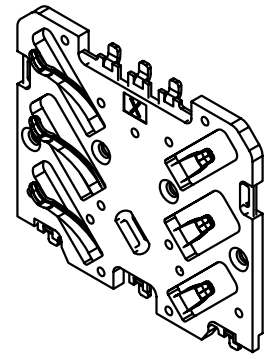
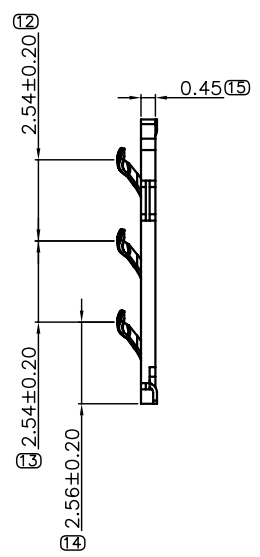
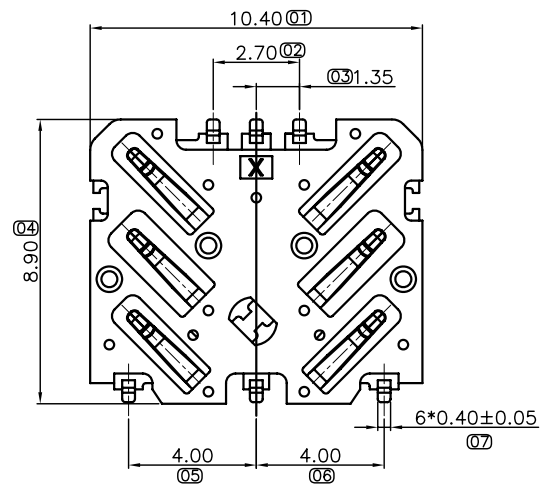
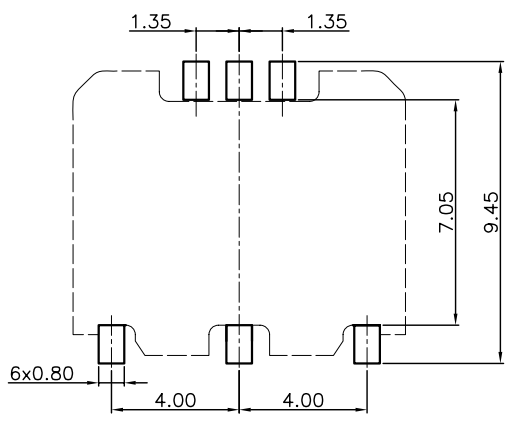
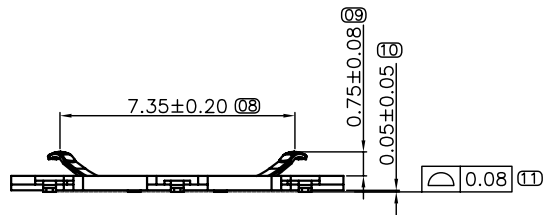


A4

REV	ECN NO	DESCRIPTION	DATE	APPD
X1		初版发行	2013.08.21	谭林红



3D VIEW



RECOMMENDED PCB LAYOUT  
(TOLERANCE +/-0.05)

NOTE:

- 1: HOUSING MATERIAL: THERMAL PLASTIC, COLOR: BLACK;
- 2: CONTACT MATERIAL: COPPER ALLOY;
- 3: PLATING:  
15u"(0.375um)Min. GOLD PLATING ON CONTACT AREA;  
100u"(2.54um)Min. MATTE-TIN PLATING ON SOLDER AREA.
- 4: PERFORMANCE:  
4.1:CONTACT RESISTANCE: 60mOHM Max.  
4.2:DIELECTRIC WITHSTANDING VOLTAGE: 200 VAC FOR 1MINUTE;  
4.3:INSULATION RESISTANCE: 1000MOHM Min.  
4.4:DURABILITY: 5000 TIMES Min.

EXTEND USE		UNIT		TITLE			
0.5H NONA SIM CARD ASSEMBLY DRAWING		mm		0.5H NONA SIM CARD ASSEMBLY DRAWING			
GENERAL TOLERANCE		MATERIAL		APPD		DWG NO	
DIMENTION		ANGLES		谭林红 2013.08.31		C-1.037A0	
. ±0.30		. ±3°		CHD		P/N:	
.0 ±0.25		.0 ±2'		谭林红 2013.08.31		1.037A0-006-5R0	
.00 ±0.20		.00 ±1'		FINISHED		SHEET	
.000 ±0.10				DRN		SCALE	
				周冬方 2013.08.21		1/1	
						REV	
						X1	